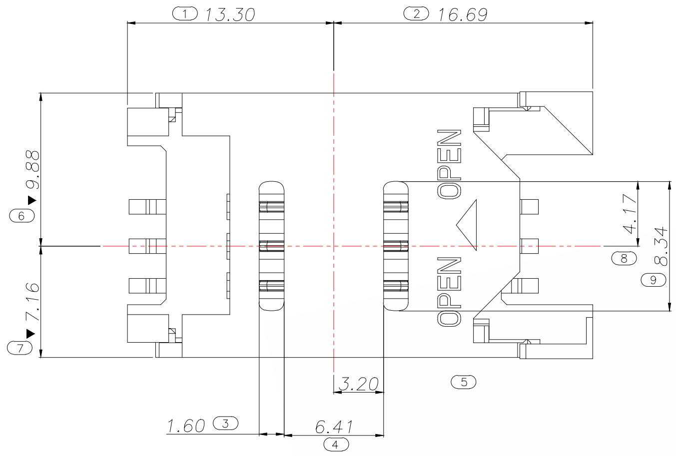
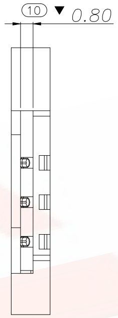
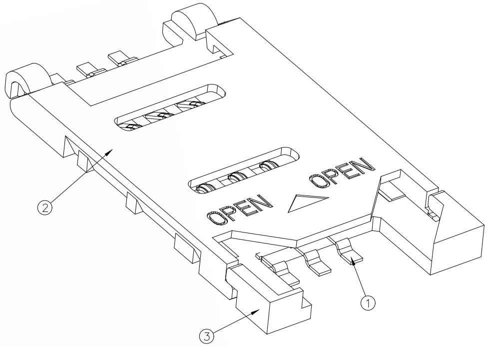
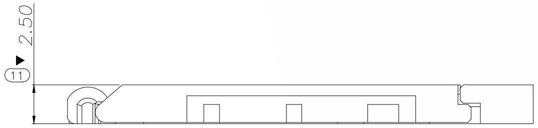
Pb Process Capable | RoHS Compliant 2011/65/EU | HF Compliant Halogen Free

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN









MINI SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

1)MATERIAL:

HOUSING: THERMOPLASTIC,UL 94V-0, COLOR:BLACK

CONTACT: COPPER ALLOY

2)FINISH

CONTACT: GOLD FLASH

SOLDER AREA: TIN 100u" Min

3)Solder-ability

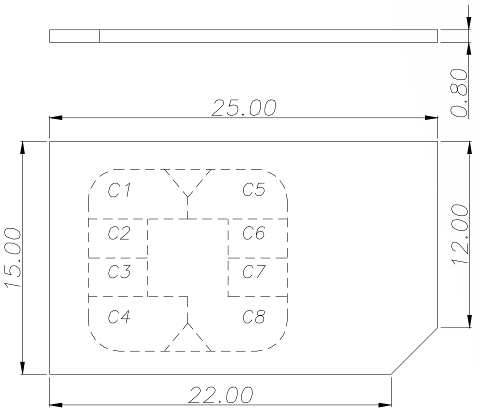
IR reflow:250°C,5sec.Max

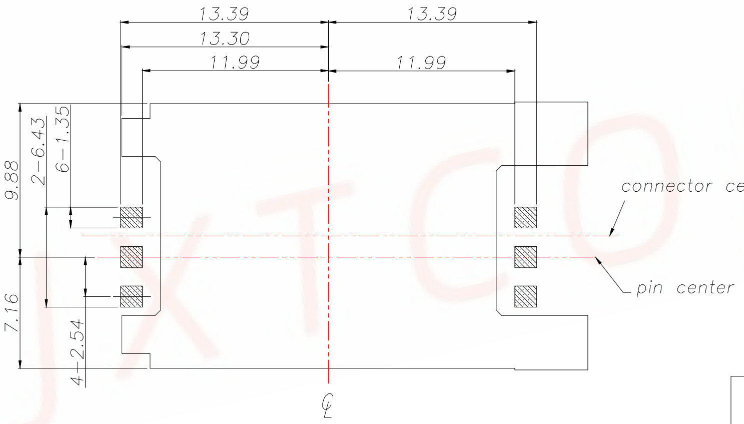
Manual soldering:350°C ,3sec.max

Ambient Temperature Range :-40°C~+85°C

Storage Temperature Range :-40°C~+85°C

Ambient Humidity Range :95% R.H. Max.





▨ PAD AREA

■ KEEP OUT AREA

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

1	Contact	COPPER ALLOY	Gold FLASH	6	
2	Cover	THERMOPLASTIC,UL 94V-0, COLOR:BLACK		1	
3	Housing	THERMOPLASTIC,UL 94V-0, COLOR:BLACK		1	
ITEM	NAME	MATERIIAL	FINISH	Q'ty	REMARK

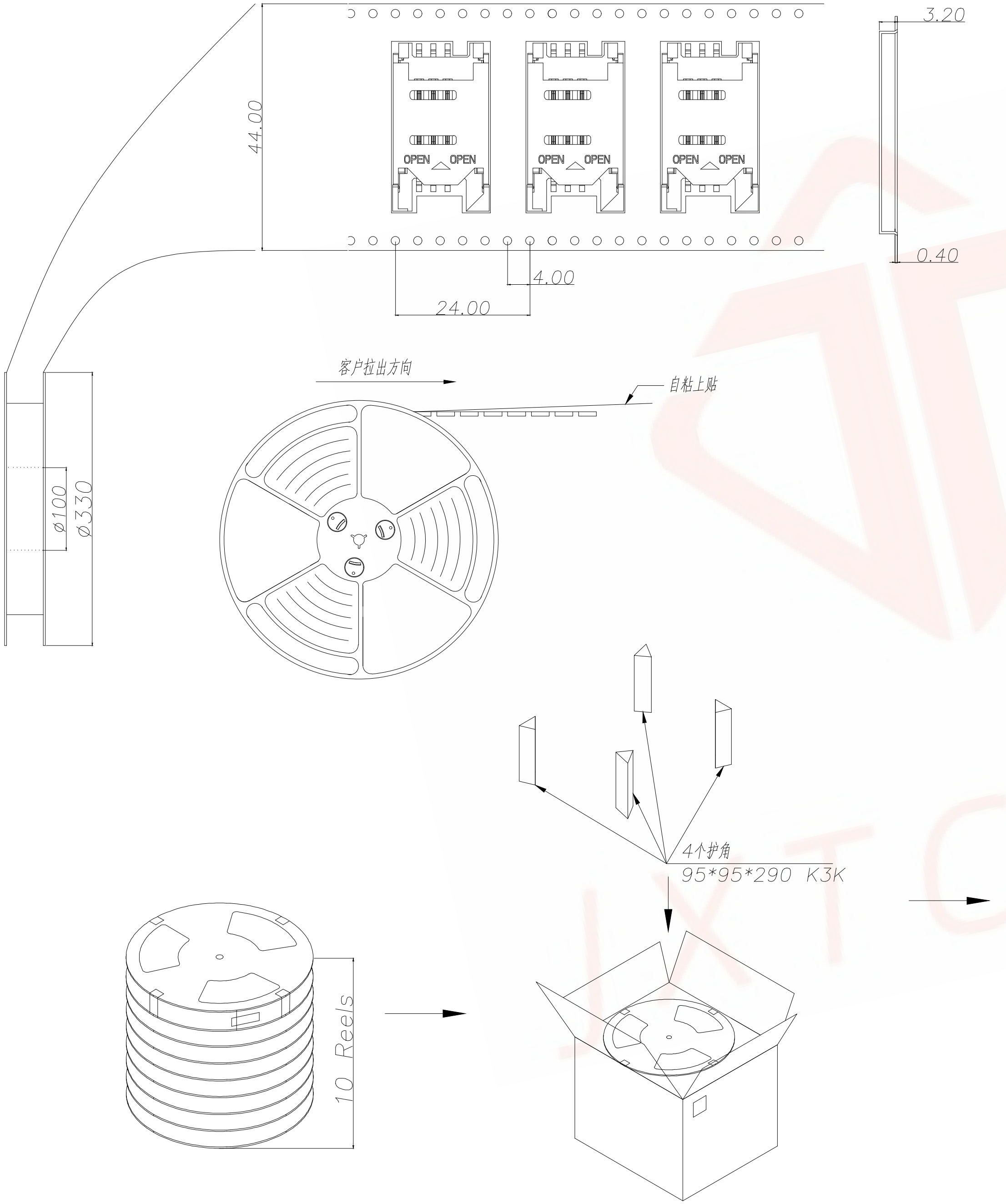
TOLERANCE		深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd	
X.:±0.50	X.°:±2°	PART NO. BSIM-011-6P	TITLE: SIM CARD CONN 掀盖式 H2.5mm
X.X:±0.30	X.X°:±1°		
X.XX:±0.20			
UNITS	mm	DESIGN: Ethan	MANUFACTURE DWG
MATERILA	— — —	CHED: Olvia	SCALE N:A
FINISH	— — —	APPD: Ava	SHEET 1/1

Pb Process Capable

RoHS Compliant 2011/65/EU

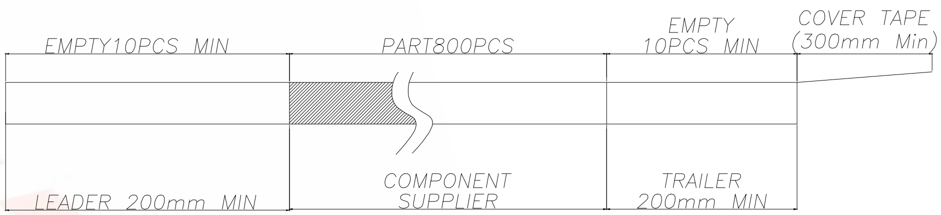
Compliant Halogen Free

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN

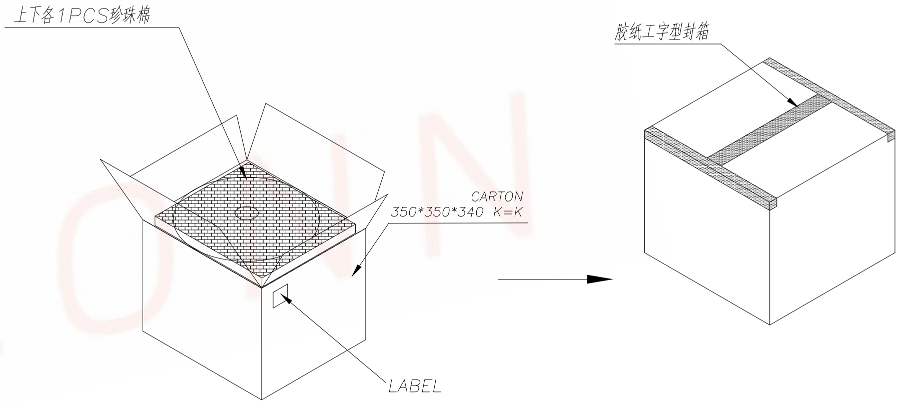


NOTES

1. NUMBER OF CONNECTORS:800PCS/REEL
2. LEAD TAPE LENGTH



3.QUANTITY:8000PCS/CARTON



TOLERANCE		深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd	
X.:±0.50	X.°:±2°	PART NO. BSIM-011-6P	TITLE: SIM CARD CONN 掀盖式 H2.5mm包装
X.X:±0.30	X.X°:±1°		
X.XX:±0.20			
UNITS	mm	DESIGN: Ethan	MANUFACTURE DWG
MATERILA	— — —	CHED: Olvia	SCALE: N:A / SHEET: 1/1
FINISH	— — —	APPD: Ava	